2SB857, 2SB858

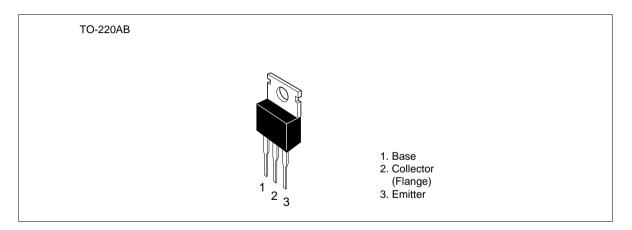
Silicon PNP Triple Diffused

HITACHI

Application

Low frequency power amplifier complementary pair with 2SD1133 and 2SD1134

Outline



Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

		Ratings			
Item	Symbol	2SB857	2SB858	Unit	
Collector to base voltage	V _{CBO}	-70	-70	V	
Collector to emitter voltage	V _{CEO}	-50	-60	V	
Emitter to base voltage	V _{EBO}	-5	-5	V	
Collector current	Ι _c	-4	-4	А	
Collector peak current	I _{C(peak)}	-8	-8	А	
Collector power dissipation	P _c * ¹	40	40	W	
Junction temperature	Tj	150	150	°C	
Storage temperature	Tstg	-45 to +150	-45 to +150	°C	

Note: 1. Value at $T_c = 25^{\circ}C$



2SB857, 2SB858

Electrical Characteristics (Ta = 25°C)

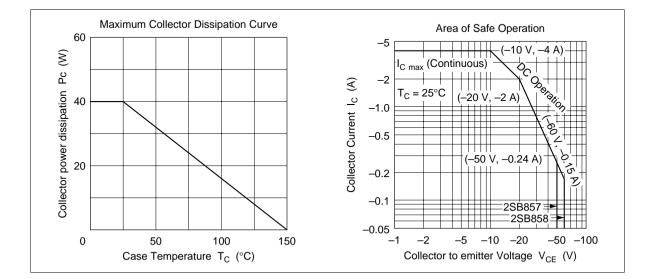
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		2SB8	57		2SB858				
Item	Symbol	Min	Тур	Max	Min	Тур	Мах	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-70	_	—	-70	_	_	V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{\scriptscriptstyle (BR)CEO}$	-50	—	—	-60	—	—	V	$I_c = -50$ mA, $R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{\rm (BR)EBO}$	-5	_	_	-5		_	V	$I_{\rm E} = -10 \ \mu A, \ I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	—	_	-1	—	—	-1	μA	$V_{_{CB}} = -50 \text{ V}, \text{ I}_{_{E}} = 0$
DC current transfer ratio	$h_{\rm FE1}^{*1}$	60	—	320	60		320		$V_{ce} = I_c = -1 A^{*2}$
	h _{FE2}	35	_		35	_	_		-4 V $I_c = -0.1 \text{ A}^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	-1	_	_	-1	V	$I_{\rm c} = -2$ A, $I_{\rm B} = -0.2$ A ^{*2}
Base to emitter voltage	V_{BE}	—	—	-1		—	-1	V	$V_{ce} = -4 V, I_c = -1 A^{*2}$
Gain bandwidth product	f _T	_	15	_	_	15	_	MHz	$V_{cE} = -4 V,$ $I_c = -0.5 A^{*2}$

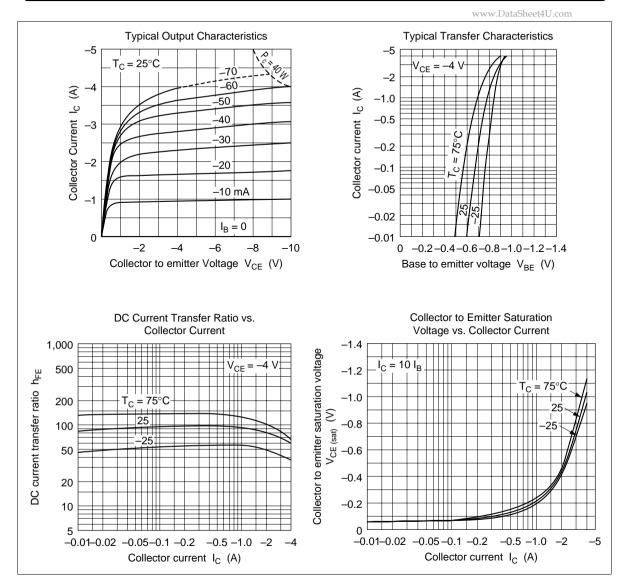
Notes: 1. The 2SB857 and 2SB858 are grouped by h_{FE1} as follows.

2. Pulse test

В	С	D
60 to 120	100 to 200	160 to 320

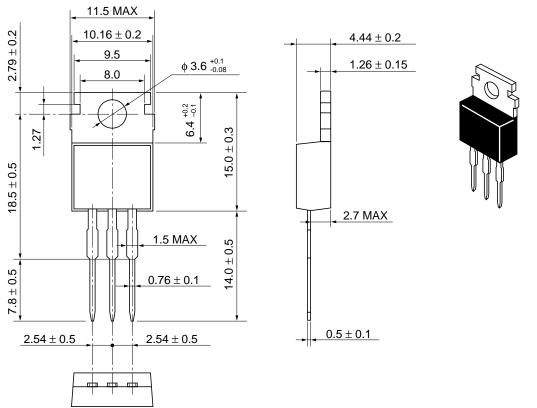


2SB857, 2SB858



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JEDEC	Conforms		
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Weight (reference value)	1.8 g		

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Semiconductor & Integrated Circuits. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109 NorthAmerica URL http:semiconductor.hitachi.com/ http://www.hitachi-eu.com/hel/ecg Europe http://www.has.hitachi.com.sg/grp3/sicd/index.htm http://www.hitachi.com.tw/E/Product/SICD_Frame.htm Asia (Singapore) Asia (Taiwan) Asia (HongKong) http://www.hitachi.com.hk/eng/bo/grp3/index.htm http://www.hitachi.co.jp/Sicd/indx.htm Japan For further information write to: Hitachi Semiconductor Hitachi Europe GmbH Hitachi Asia Pte. Ltd. (America) Inc. Electronic components Group 16 Collyer Quay #20-00

 (America) Inc.
 Ele

 179 East Tasman Drive,
 Dor

 San Jose, CA 95134
 D-8

 Tel: <1> (408) 433-1990
 Ger

 Fax: <1>(408) 433-0223
 Tel:

 Fax:
 Hitz

Electronic components Group Dornacher Stra§e 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322 Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd. Taipei Branch Office 3F, Hung Kuo Building. No.167, Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218 Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

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